



Attorney Docket No.: 5649-553DV

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re: Hyae-Ryoung Lee

Group Art Unit: 2815

Serial No.: 09/800,138

Examiner: Paul E. Brock II

Filed: March 6, 2001

For: METHODS OF FORMING INTEGRATED BONDING PADS INCLUDNIG
CLOSED VIAS AND CLOSED CONDUCTIVE PATTERNS

August 13, 2002

Box RCE
Commissioner for Patents
Washington, DC 20231

#9/D
Amdt
J. McNeill
9/5/02
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AMENDMENT ACCOMPANYING RCE

Sir:

This Amendment is responsive to the Final Official Action of May 31, 2002.

The present amendment also includes a section entitled "**VERSION WITH MARKINGS TO SHOW CHANGES MADE**" attached hereto. Please enter the following Amendment before examining the present Request for Continued Examination ("RCE") application.

In the Claims:

Please replace Claims 35 and 40 with the following like numbered claims:

35. (Amended) A method of forming a bonding pad for an integrated circuit comprising the steps of:

forming a dielectric layer having first and second opposing faces on an integrated circuit substrate, the dielectric layer including a closed via therein that extends from the first face to the second face and that encloses an inner portion of the dielectric layer, and is enclosed by an outer portion of the dielectric layer; and

forming a conductive pattern that extends from the first face to the second face in the closed via and on the dielectric layer opposite the substrate.

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